Special Issue

Neuromorphic Chips at the Intersection of Neuroscience, Electronics and AI

Message from the Guest Editors

Neuromorphic chips—integrating concepts from neuroscience, electronics, and artificial intelligence—are revolutionizing the landscape of intelligent hardware and computing systems. By mimicking the neural structures and processes of the brain, neuromorphic devices offer new opportunities for efficient, adaptive, and low-power computation well-suited for edge AI, brain–computer interfaces, robotics, sensory processing, and more. This Special Issue aims to showcase recent breakthroughs in neuromorphic hardware and systems at the intersection of neuroscience, electronics, and AI. We welcome submissions covering innovative circuit and system designs, emerging device technologies, brain-inspired algorithms, in-memory and event-driven computing, sensory processing hardware, and real-world applications of neuromorphic chips. We particularly encourage interdisciplinary works that highlight the synergy among neuroscience, microelectronics, and artificial intelligence.

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Deadline for manuscript submissions

30 April 2026

Chips

an Open Access Journal by MDPI

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About the Journal

Message from the Editor-in-Chief

Chips is a new journal with the aim to become a leading reference on all aspects of the IC domain. The journal is devoted to publishing rigorously peer-reviewed articles (such as original research, reviews, and communications) with the specific target to disseminate novelties in terms of research and knowledge as well as the most advanced state of the art on IC technologies, design, testing, and production. The journal offers the opportunity to actively spread new concepts and advancements in the IC domain and its increasing interrelated and multidisciplinary areas in a timely manner. More specifically, the journal will cover chip design, including CAD tools, chip production, and their wide spectrum of applications.

Editor-in-Chief

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